

STPS30100ST

Power Schottky rectifier

Main product characteristics

I _{F(AV)}	30 A
V _{RRM}	100 V
T _j (max)	150° C
V _F (typ)	0.385 V

Features and Benefits

- Avalanche rated
- Low V_F
- Good trade off between leakage current and forward voltage drop
- High frequency operation
- Avalanche capability specified

Description

Single Schottky rectifier, suited for high frequency switch mode power supply.

Packaged in TO-220AB, this device is intended to be used in notebook and game station adaptors, providing in these applications a good efficiency at both low and high load.

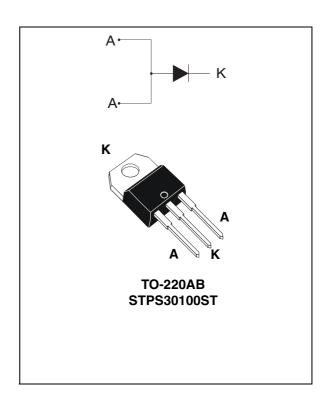


Table 1. Absolute Ratings (limiting values)

Symbol	Paramet	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage	100	V	
I _{F(RMS)}	RMS forward current	60	Α	
I _{F(AV)}	Average forward current $\delta = 0.5$	T _c = 125° C	30	Α
I _{FSM}	Surge non repetitive forward current	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$		Α
P _{ARM}	Repetitive peak avalanche power	nche power $t_p = 1 \mu s T_j = 25^{\circ} C$		W
T _{stg}	Storage temperature range	-65 to + 175	°C	
T _j	Maximum operating junction temperature	150	°C	

^{1.} $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Characteristics STPS30100ST

Characteristics 1

Table 2. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case	1	°C/W

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test Cor	Min.	Тур.	Max.	Unit	
I _R ⁽¹⁾	I _R ⁽¹⁾ Reverse leakage current	T _j = 25° C	$V_R = V_{RRM}$			175	μΑ
		T _j = 125° C			20	50	mA
		T _j = 25° C	V _R = 70 V			60	μΑ
l		T _j = 125° C			10	20	mA
	Forward voltage drop	T _j = 25° C	I _F = 5 A		0.475		
		T _j = 125° C			0.385		
		$T_j = 25^{\circ} C$	I _F = 10 A		0.555		
V _F ⁽²⁾		T _j = 125° C			0.475		V
		$T_j = 25^{\circ} C$	I _F = 15 A		0.620	0.660	
		T _j = 125° C			0.525	0.565	
		$T_j = 25^{\circ} C$	I _F = 30 A		0.740	0.800	
		T _j = 125° C			0.605	0.655	

^{1.} Pulse test: $t_p = 5 \text{ ms}, \delta < 2\%$

To evaluate the conduction losses use the following equation: P = 0.475 x $I_{F(AV)}$ + 0.006 x $I_{F}^{2}_{(RMS)}$

$$P = 0.475 \times I_{F(AV)} + 0.006 \times I_{F^{2}(RMS)}^{2}$$

^{2.} Pulse test: t_p = 380 μ s, δ < 2%

STPS30100ST Characteristics

Figure 1. Conduction losses versus average Figure 2. Average forward current versus current ambient temperature (δ = 0.5)

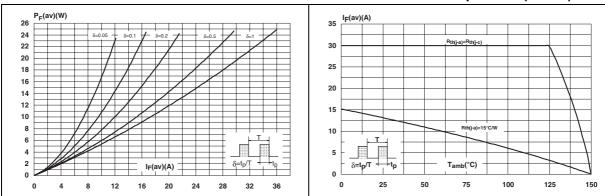


Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Normalized avalanche power derating versus junction temperature

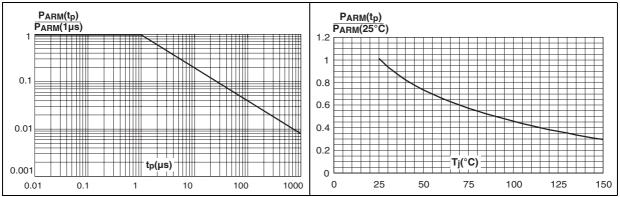
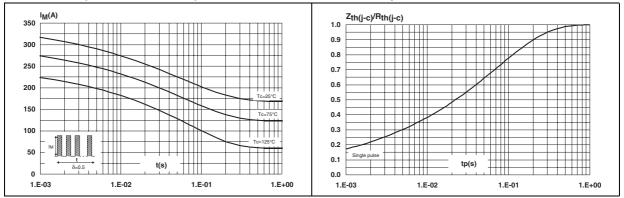


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

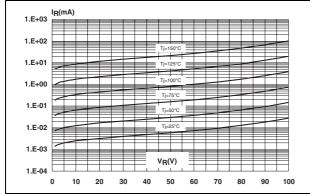
Figure 6. Relative variation of thermal impedance junction to case versus pulse duration



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Figure 7. Reverse leakage current versus reverse voltage applied (typical values)

Figure 8. Junction capacitance versus reverse voltage applied (typical values)



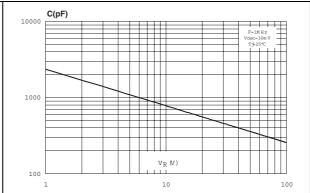
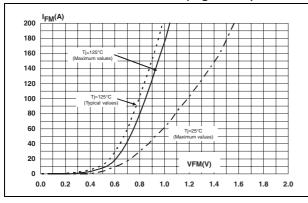
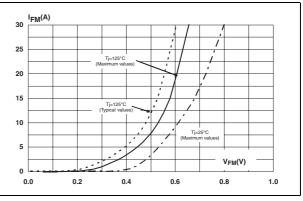


Figure 9. Forward voltage drop versus forward current (high level)

Figure 10. Forward voltage drop versus forward current (low level)



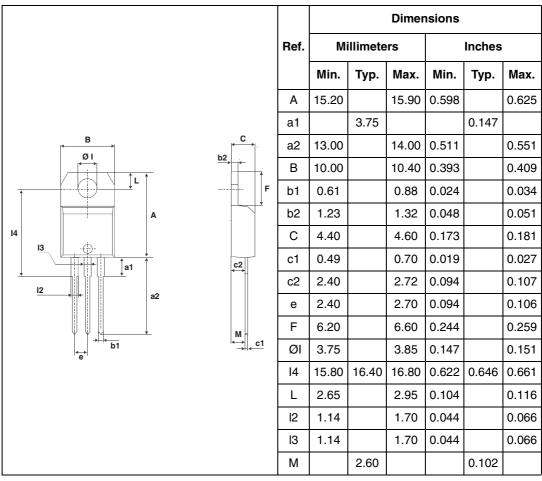


STPS30100ST Package Information

2 Package Information

Epoxy meets UL94,V0

Table 4. TO-220AB dimensions



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

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Ordering Information STPS30100ST

3 Ordering Information

Ordering type Marking		Package	Weight	Base qty	Delivery mode
STPS30100ST	PS30100ST STPS30100ST		2.23 g	50	Tube

4 Revision History

Date	Revision	Changes
24-Oct-2006	1	First issue

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